

PART INFORMATION

Mfg Item Number	MPC755CPX400LE
Mfg Item Name	FCPBGA 360 25SQ*2.7P1.27

SUPPLIER

Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2017-06-06
Response Document ID	5265K00108D021A1.23
Contact Name	Freescale Semiconductor Inc
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URL for Additional Information	www.freescale.com

DECLARATION

EU RoHS	No
Pb Free	No
HalogenFree	Yes
Plating Indicator	e0
EU RoHS Exemption(s)	15

MANUFACTURING

Mfg Item Number	MPC755CPX400LE
Mfg Item Name	FCPBGA 360 25SQ*2.7P1.27
Version	ALL
Weight	2.484700
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	3
Peak Processing Temperature	245 C
Max Time at Peak Temperature	30 seconds
Number of Processing Cycles	3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	3 - Item(s) does not contain RoHS restricted substances per the definition above except for lead in solders and selected exemptions, if any
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
	15:Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages
List of Freescale Accepted Exemptions	<p>6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight</p> <p>6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight</p> <p>6(c) : Copper alloy containing up to 4% lead by weight</p> <p>7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)</p> <p>7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications</p> <p>7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound</p> <p>7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher</p> <p>7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC</p> <p>7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors</p> <p>15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages</p>

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%	ARTICLEPPM	ARTICLE%
Underfill	0.1256	Solvents, additives, and other materials	Methylhexahydrophthalic anhydride	25550-51-0		0.01897376	g	151065	15.1065	7636	0.7636
Underfill		Plastics/polymers	1,3-bis(2,3-epoxypropoxy)-2,2-dimethylpropane	17557-23-2		0.00699529	g	55695	5.5695	2815	0.2815
Underfill		Plastics/polymers	1,6-Bis(2,3-epoxypropoxy) naphthalene	27610-48-6		0.00699529	g	55695	5.5695	2815	0.2815
Underfill		Plastics/polymers	Elastomer Modified Diglycidyl Ether	68809-14-8		0.00699529	g	55695	5.5695	2815	0.2815
Underfill		Glass	Silica, crystalline - quartz (SiO2)	14808-60-7		0.0819893	g	652781	65.2781	32997	3.2997
Underfill		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%)	-		0.00365107	g	29069	2.9069	1469	0.1469
Capacitor_0201	0.0408						g				
Capacitor_0201		Metals	Copper, metal	7440-50-8		0.002856	g	70000	7	1149	0.1149
Capacitor_0201		Nickel (external applications only)	Nickel	7440-02-0		0.0086496	g	212000	21.2	3481	0.3481
Capacitor_0201		Metals	Tin, metal	7440-31-5		0.0002448	g	6000	0.6	98	0.0098
Capacitor_0201		Metals	Barium titanate	12047-27-7		0.0290496	g	712000	71.2	11691	1.1691
Solder Balls - Low Lead	0.7127						g				
Solder Balls - Low Lead		Metals	Aluminum, metal	7429-90-5		0.0000057	g	8	0.0008	2	0.0002
Solder Balls - Low Lead		Antimony/Antimony Compounds	Antimony (metallic)	7440-36-0		0.00000499	g	7	0.0007	2	0.0002
Solder Balls - Low Lead		Arsenic/Arsenic Compounds	Arsenic	7440-38-2		0.00001425	g	20	0.002	5	0.0005
Solder Balls - Low Lead		Bismuth/Bismuth Compounds	Bismuth	7440-69-9		0.00000784	g	11	0.0011	3	0.0003
Solder Balls - Low Lead		Metals	Copper, metal	7440-50-8		0.00000713	g	10	0.001	2	0.0002
Solder Balls - Low Lead		Metals	Iron, metal	7439-89-6		0.00001212	g	17	0.0017	4	0.0004
Solder Balls - Low Lead		Lead/Lead Compounds	Lead	7439-92-1		0.25658483	g	360018	36.0018	103265	10.3265
Solder Balls - Low Lead		Nickel (external applications only)	Nickel	7440-02-0		0.00002637	g	37	0.0037	10	0.001
Solder Balls - Low Lead		Metals	Silver, metal	7440-22-4		0.01419556	g	19918	1.9918	5713	0.5713
Solder Balls - Low Lead		Metals	Tin, metal	7440-31-5		0.44183622	g	619947	61.9947	177822	17.7822
Solder Balls - Low Lead		Metals	Zinc, metal	7440-66-6		0.00000499	g	7	0.0007	2	0.0002
High Pb Bumped Semiconductor D	0.0956				15		g				
High Pb Bumped Semiconductor D		Lead/Lead Compounds	Lead	7439-92-1		0.00900332	g	94177	9.4177	3623	0.3623
High Pb Bumped Semiconductor D		Nickel (external applications only)	Nickel	7440-02-0		0.00007887	g	825	0.0825	31	0.0031
High Pb Bumped Semiconductor D		Metals	Tin, metal	7440-31-5		0.00047379	g	4956	0.4956	190	0.019
High Pb Bumped Semiconductor D		Metals	Titanium, metal	7440-32-6		0.00000402	g	42	0.0042	1	0.0001
High Pb Bumped Semiconductor D		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%)	-		0.0008604	g	9000	0.9	346	0.0346
High Pb Bumped Semiconductor D		Glass	Silicon, doped	-		0.0851796	g	891000	89.1	34281	3.4281
Capacitor Solder Paste	0.0117						g				
Capacitor Solder Paste		Metals	Copper, metal	7440-50-8		0.0000585	g	5000	0.5	23	0.0023
Capacitor Solder Paste		Lead/Lead Compounds	Lead	7439-92-1		0.00000097	g	83	0.0083	0	0
Capacitor Solder Paste		Metals	Silver, metal	7440-22-4		0.000351	g	30000	3	141	0.0141
Capacitor Solder Paste		Metals	Tin, metal	7440-31-5		0.01128953	g	964917	96.4917	4543	0.4543
Substrate	1.4983						g				
Substrate		Metals	Copper, metal	7440-50-8		0.47392278	g	316307	31.6307	190736	19.0736
Substrate		Plastics/polymers	Other Epoxy resins	-		0.48438541	g	323290	32.329	194965	19.4965
Substrate		Lead/Lead Compounds	Lead	7439-92-1		0.00028018	g	187	0.0187	112	0.0112
Substrate		Glass	Fiberglass	-		0.47413104	g	316446	31.6446	190820	19.082
Substrate		Glass	Other silica compounds	-		0.04604126	g	30729	3.0729	18529	1.8529
Substrate		Metals	Silver, metal	7440-22-4		0.01896398	g	12657	1.2657	7632	0.7632
Substrate		Metals	Tin, metal	7440-31-5		0.00057535	g	384	0.0384	231	0.0231

LINKS

MCD LINK	
NXP website	http://www.nxp.com
GENERAL ENVIRONMENTAL COMPLIANCE LINKS	
RoHS signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf
China RoHS	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY
REACH signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf
ELV signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf
Conflict Minerals statement	http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf
NXP ENVIRONMENTAL INFORMATION	
Environmental Compliance website	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX
FAQ	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ
Technical Service Request	http://www.nxp.com/support/sales-and-support:SUPPORTHOME
LINKS TO BLANK IPC1752 FORMS	
Blank IPC1752 v1.1 Form	http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

IPC1752 XML LINKS

http://www.freescale.com/mcdfs/MPC755CPX400LE_IPC1752_v11.xml

http://www.freescale.com/mcdfs/MPC755CPX400LE_IPC1752A.xml